# Call for Papers International Conference in Newer Concepts in Engineering and Technology (iConnect 2K17)

# Special Issue on "Newer Concepts in Engineering and Technology"

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#### **About the Issue**

The special issue will include full research papers, short communications and critical reviews on various topics dealing with wide range of sub fields of Engineering Sciences. The subject areas include, but are not limited to: Chemical Engineering, Civil Engineering, Computer Engineering, Communication Engineering, Control Systems, Construction Engineering, Electrical Engineering, Electronics Engineering, Embedded Systems, Environmental Engineering, Industrial Engineering, Instrumentation Technology, Mechanical Engineering, Mechatronics, Network and Protocols, Wireless Communication, Nano Physics etc.,

# **Important Dates**

Submission Deadline: 31.03.2017 Acceptance Notification: 12.04.2017 Final Manuscript Due: 02.05.2017 Publication Date: 10.06.2017

## **Guidelines for Submission**

Please visit journal website (www.iioab.org) for more information about the Journal's policies and submission process. Use IIOABJ template for the preparation of the manuscripts. For details refer, "Instruction to the Authors" at: http://www.iioab.org/guideforauthors.htm

#### **How to Submit**

To submit an article to this special Issue, please send the manuscript to the guest editor at: vijayan.me@gmail.com AND copy (cc) to journal.iioab@gmail.com . Please mention that the submission is for special issue "iConnect 2K17" in the subject line of the email and in the cover letter.